

Amendments to the Specification:

Please replace the title as follows:

~~STAGE DRIVE METHOD AND STAGE DRIVE APPARATUS, EXPOSURE~~

~~APPARATUS, AND DEVICE PRODUCING METHOD~~

STAGE DRIVE METHOD AND STAGE UNIT, EXPOSURE APPARATUS, AND

DEVICE MANUFACTURING MEHTOD

Please replace the paragraph beginning at page 24, line 25 with the following amended paragraph:

FIG. 1 schematically shows the entire configuration of an exposure apparatus 100 related to the first embodiment. Exposure apparatus 100 is a projection exposure apparatus by the step-and-scan method, that is, the so-called scanning stepper (also called a scanner). Exposure apparatus 100 is equipped with illumination system 10, a reticle stage RST that holds a reticle R serving as a mask, a projection unit PU, a wafer stage unit 50 that has wafer stages WST1 and WST2, off-axis alignment systems ALG1 and ALG2, ~~serving as a first and a second mark detection system~~, a control system for these components or assemblies, and the like. On wafer stages WST1 and WST2, substrates serving as wafers are to be mounted. In FIG. 1, a wafer W1 is mounted on wafer stage WST1, and a wafer W2 is mounted on wafer stage WST2.

Please replace the paragraph beginning at page 30, line 3 with the following amended paragraph:

Wafer stage unit 50 is equipped with a base platform 12, wafer stages WST1 and WST2 arranged above the upper surface of base platform 12, an interferometer system 118 (refer to FIG. 5) ~~serving as a position measuring unit~~ that includes interferometers 16 and 18 for measuring the positions of wafer stages WST1 and WST2, and a wafer stage drive section 124 (refer to FIG.5) for driving wafer stages WST1 and WST2.

Please replace the paragraph beginning at page 39, line 6 with the following amended paragraph:

Further, when wafer stage WST2 is in the first area of projection optical system PL and exposure of the wafer on wafer stage WST2 is to be performed, the position of wafer stage WST1 is controlled by X-axis interferometer 16 and Y-axis interferometer 46. In the description below, the coordinate system set by the measurement axes of X-axis interferometer 16 and Y-axis interferometer 46 will be referred to as a second exposure coordinate system.

Please replace the paragraph beginning at page 67, line 14 with the following amended paragraph:

In the second embodiment, instead of wafer stage unit 50 described earlier, a wafer stage unit 50' shown in FIG. 12 is arranged. As is shown in FIG. 12, wafer stage unit 50' is equipped with a base platform 12, wafer stage WST1' and wafer stage WST2' arranged above (the front side of the page surface of FIG. 12) the upper surface of base platform 12, six interferometers 151X₁, 151X₂, 151X₃, 151X₄, 151Y₁, and 151Y₂ serving as position measuring unit for measuring the positions of wafer stages WST1' and WST2', a first drive section 171 and a second drive section 172 shaped roughly in a letter H in a planar view (when viewed from above) that individually drive wafer stages WST1' and WST2', and a first connecting mechanism 195 and a second connecting mechanism 196 (not shown in FIG. 12, refer to FIG. 11).

Please replace the paragraph beginning at page 72, line 12 with the following amended paragraph:

Further, as is shown in FIG. 12, an alignment system ALG serving as a mark detection system is arranged on the -Y side of projection optical system PL a predetermined distance away.

Please replace the Abstract with the attached amended Abstract.